AGI designs and manufactures Selective Wave Solder Pallets with Titanium for complex soldering applications. Using Titanium in your pallet will reduce the number of areas that will require touch up or 2nd-hand loading of parts. A common application, PCB’s that are designed with plated through hole components in very close proximity to bottom side surface mount components. Machined Titanium can achieve “seal walls” down to 0.020” thick standard and 0.015” thick over short distances versus the 0.030” allowable in Composites. This allows for more leads to be exposed while still keeping the bottom side components masked from the wave solder.

Our proven design and machining techniques allow the use of Titanium in small areas. Our Inserts are designed to overlap the Composite creating good seals and prevent leaking of solder. By only using Titanium in small areas, your pallet maintains a more consistent thermal property and requires less preheating than a full Titanium pallet.

FEATURES AND BENEFITS

- Reduces the number of areas that will require touch up.
- Seal Walls down to 0.020” thick standard, down to 0.015” thick for short distances.
- Composite frame reduces thermal load in wave, cooler and lighter than Titanium.
- Small Inserts used to target problem areas.
- Titanium ensures long life for high volume applications.
- Ideal for soldering very challenging mixed technology boards.